

## Features

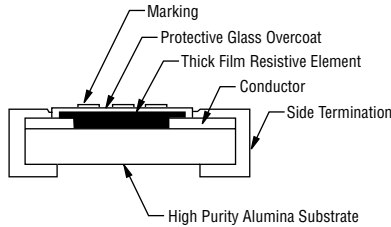
- Lead free version available (see How to Order "Termination" options)
- RoHS compliant\*
- 4 isolated resistors in an 0804 size package
- E24 series from 10 ohms to 1 megohm
- Concave termination style
- Resistance tolerance  $\pm 5\%$
- Suitable for most types of soldering processes
- Paper tape on plastic reel for automatic placement

## Model CAT10 - Chip Resistor Array

### Characteristics

Number of Elements.....4 (isolated)  
 Power Rating per Resistor @ 70 °C  
 .....31 mW  
 Package Power Rating @ 70 °C..125 mW  
 Operating Temperature Range  
 .....-55 °C to +125 °C  
 Derated to 0 Load @.....+125 °C  
 Max. Working Voltage.....25 V  
 Max. Overload Voltage.....50 V  
 Resistance Tolerance..... $\pm 5\%$   
 Resistance Range/E24 Series  
 .....10 ohms to 1 megohm  
 plus Zero-ohm Jumper  
 T.C.R..... $\pm 250$  ppm/°C  
 Packaging .....10,000 pieces per reel

### Construction

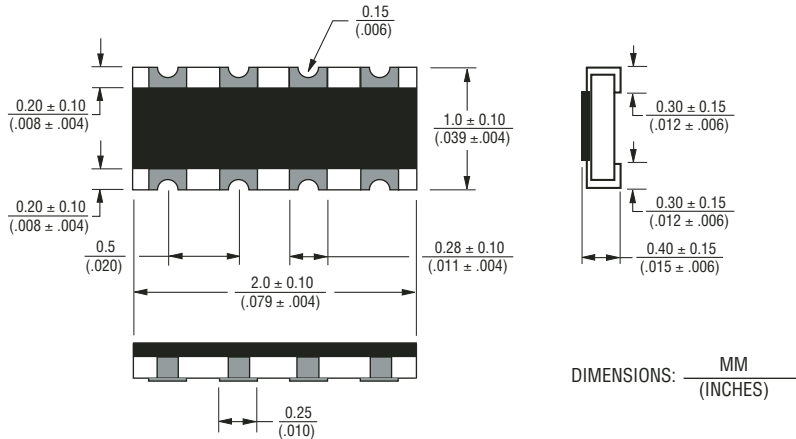


### How To Order

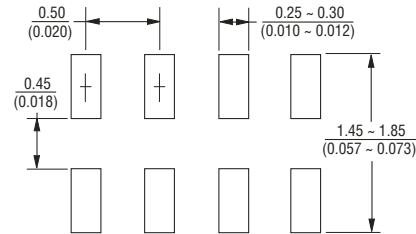
**CA T 10 - 103 J 4**

Chip Arrays \_\_\_\_\_  
 Type \_\_\_\_\_  
 • T = Concave  
 Model \_\_\_\_\_  
 • 10 = 0804 Package Size  
 Resistance Code \_\_\_\_\_  
 • 103 = 10K ohms  
 • 000 = Zero-ohm Jumper  
 Resistance Tolerance \_\_\_\_\_  
 • J =  $\pm 5\%$   
 Resistors \_\_\_\_\_  
 • 4 = 4 pcs.  
 Terminations \_\_\_\_\_  
 • LF = Tin-plated (lead free)  
 • Blank = Solder-plated

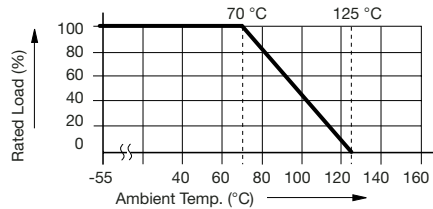
### Product Dimensions



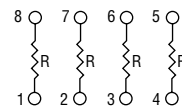
### Land Pattern



### Derating Curve



### Isolated Circuit



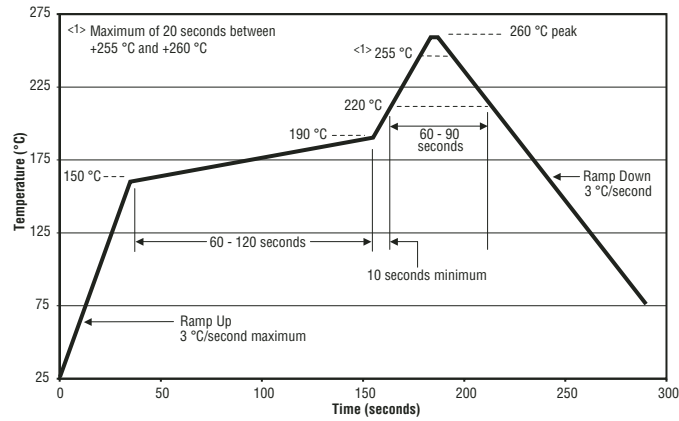
For Standard Values Used in Capacitors, Inductors, and Resistors, [click here](#).

\*RoHS Directive 2002/95/EC Jan 27 2003 including Annex  
 Specifications are subject to change without notice.  
 Customers should verify actual device performance in their specific applications.

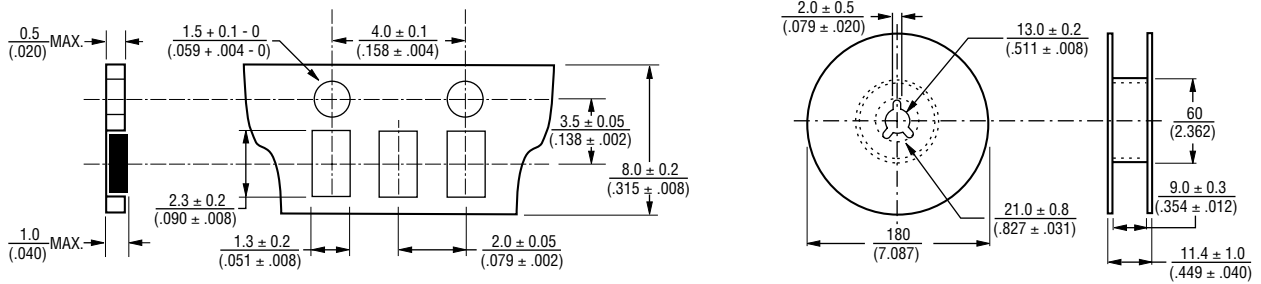
# Model CAT10 - Chip Resistor Array

**BOURNS®**

## Soldering Profile for Lead Free Chip Resistors and Arrays



## Packaging Dimensions



REV. 04/06

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